

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 5985 | (semiconductor adj (chip or die)) and (through adj hole) and resin | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/05 10:31 |
| L2 | 453 | (semiconductor adj (chip or die)) and (through adj hole) and resin and (conductive adj pattern) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/05 10:52 |
| L3 | 5187 | (semiconductor adj (chip or die)) and (through adj hole) and resin and (plurality of electrodes) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/05 10:32 |
| L4 | 759 | (semiconductor adj (chip or die)) and (through adj hole) and resin and (inner adj leads) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/05 10:33 |
| L5 | 1905 | (semiconductor adj (chip or die)) and (through adj hole) and resin and (insulating adj (film or layer)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/05 10:34 |
| L6 | 2 | "5736780".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/05 10:52 |